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7/23/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Takehito USHIKI; Hitoshi TSUNODA

Serial No: Not Assigned [parent 09/346,004]

Filed: December 11, 2001

For: SEMICONDUCTOR WAFER,
METHOD FOR PRODUCING THE
SAME, AND WAFER CHUCK

Art Unit: Not Assigned

Examiner: Not Assigned

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified divisional application, please amend the application as follows:

IN THE CLAIMS:

Rewrite claim 14 as follows:

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14. (Amended) A method for producing a semiconductor wafer by polishing a surface of the semiconductor wafer which is held at its back surface, which determines a back surface profile and analyzes its frequency at least before holding the semiconductor wafer and polishes a semiconductor wafer having undulation components on wafer back surface of $10 \mu\text{m}^3$ or less represented in terms of power spectrum density at least for the components at a wavelength of 10 mm and/or a